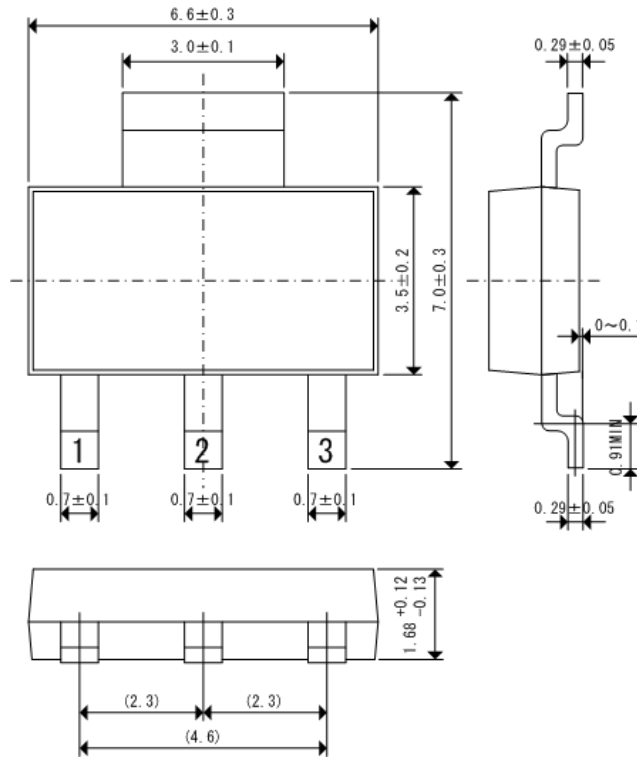


Packaging Information / Reference Pattern Layout Dimensions

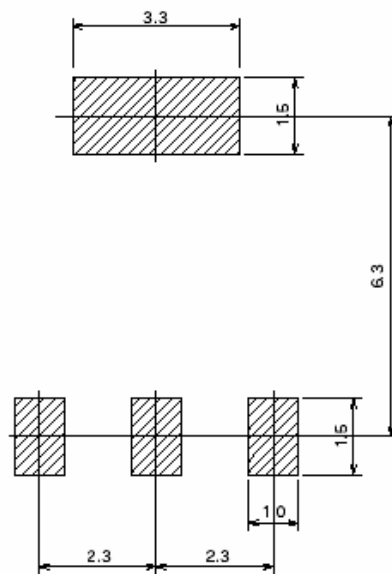
● SOT-223

Unit: mm

■ Packaging Information



■ Reference Pattern Layout Dimension

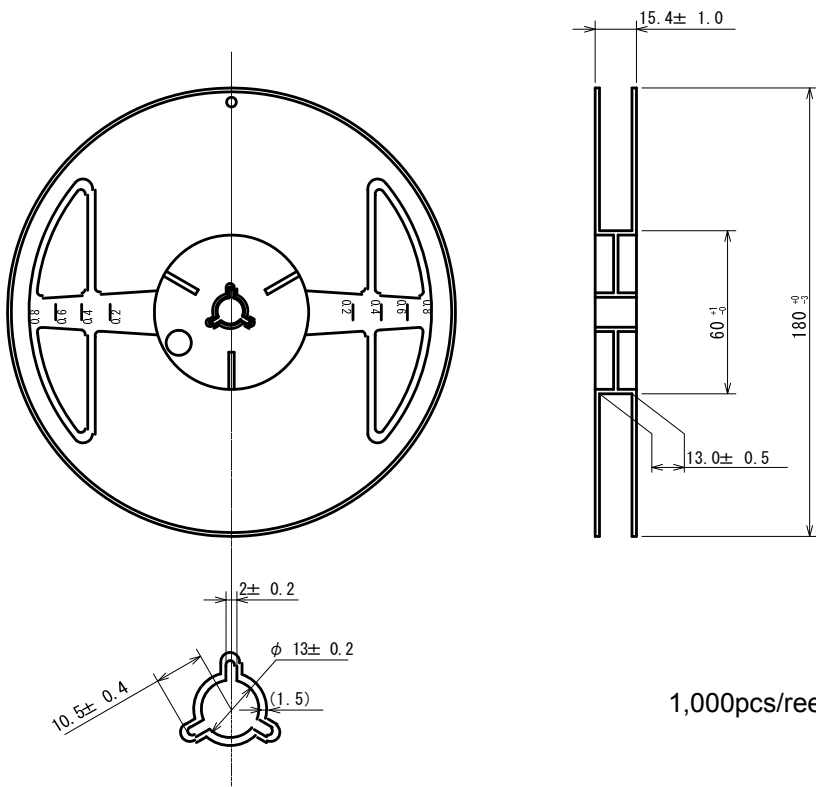


テーピング仕様 / Taping Specifications

SOT-223

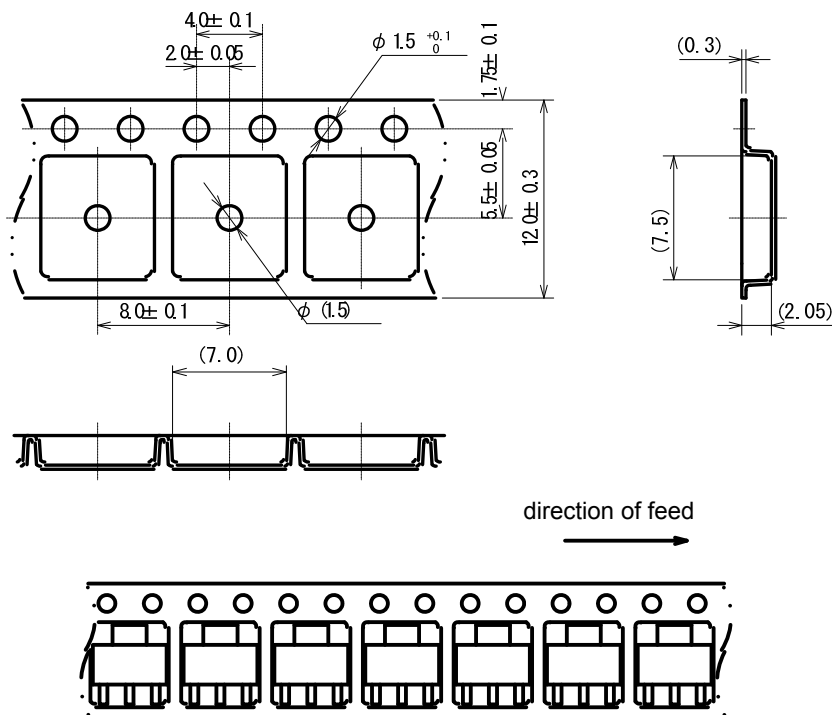
●リール/Reel

Unit: mm



1,000pcs/reel

●テーピング仕様/Taping Specifications



direction of feed



R Type : [Device orientation : Right]

Standard feed

● **SOT-223 Power Dissipation**

Power dissipation data for the SOT-223 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board: Dimensions 40 x 40 mm (1600 mm<sup>2</sup> in one side)

Copper (Cu) traces occupy 50% of the board area

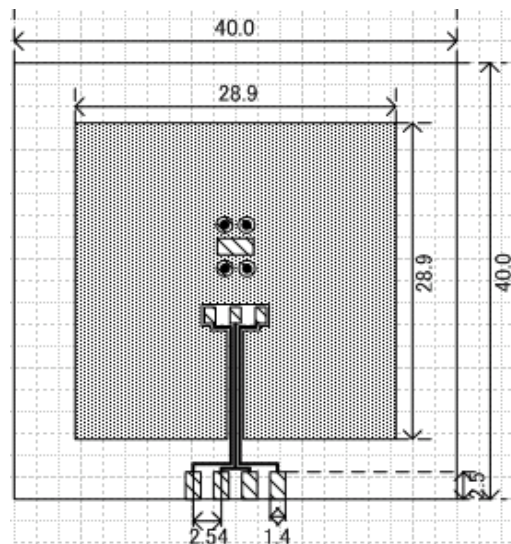
In top and back faces

Package heat-sink is tied to the copper traces

Material: Glass Epoxy (FR-4)

Thickness: 1.6 mm

Through-hole: 4 x 0.8 Diameter

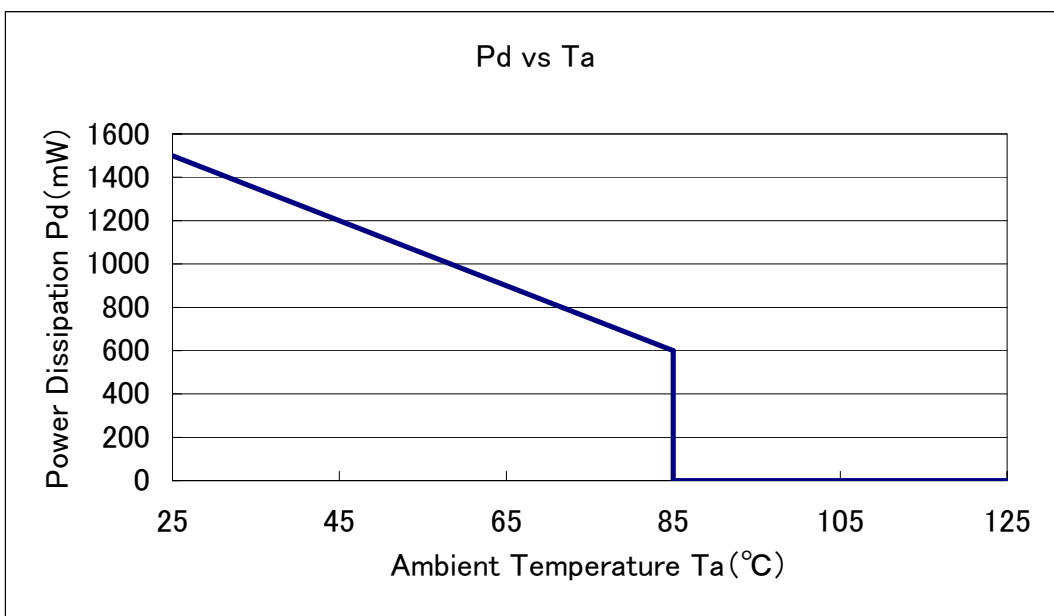


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

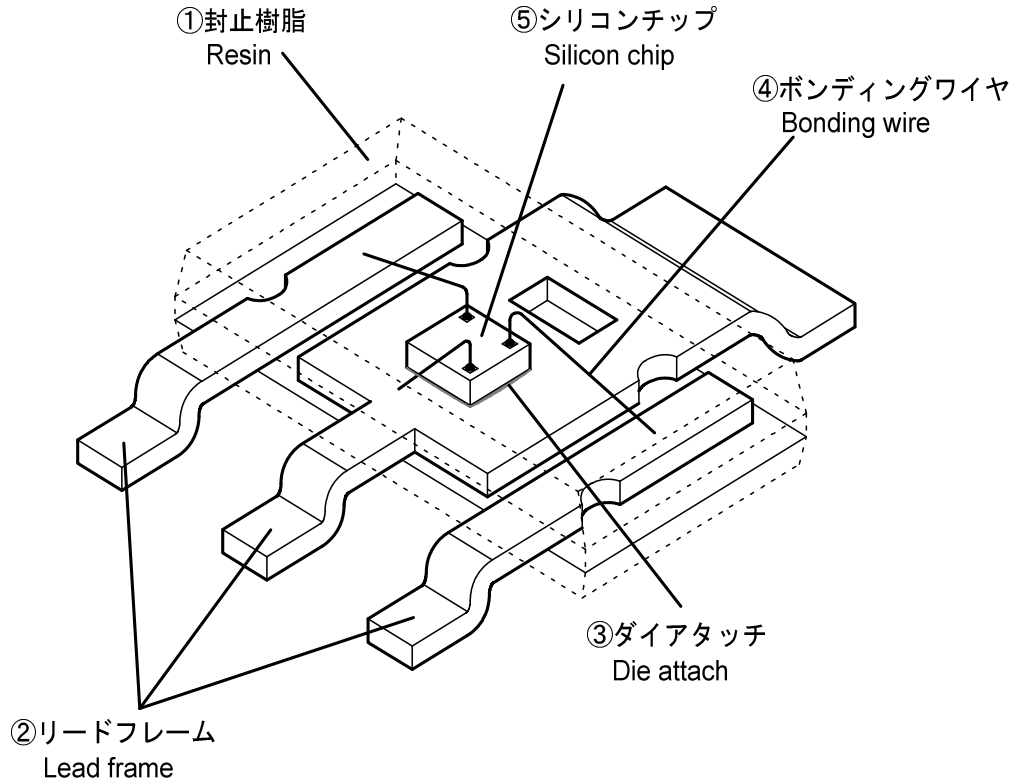
Board Mount ( $T_j \text{ max} = 125^\circ\text{C}$ )

| Ambient Temperature ( $^\circ\text{C}$ ) | Power Dissipation $P_d$ (mW) | Thermal Resistance ( $^\circ\text{C}/\text{W}$ ) |
|--|------------------------------|--|
| 25                                       | 1500                         | 66.67  |
| 85                                       | 600                          |  |



SOT-223構造図  
SOT-223 Perspective

RoHS対応品  
RoHS Compliance



| 項目<br>Item                     | 材料<br>Material                             | 備考<br>Note                            |
|--------------------------------|--|---------------------------------------|
| ①<br>封止樹脂<br>Resin             | エポキシ樹脂<br>Epoxy resin                      | 難燃グレード/Flammability rating<br>UL94V-0 |
| ②<br>リードフレーム<br>Lead frame     | 銅系<br>Copper alloy                         |                                       |
| 端子処理<br>Lead plating           | 鉛フリーはんだメッキ<br>Lead(Pb) free solder plating |                                       |
| ③<br>ダイアタッチ<br>Die attach      | エポキシ<br>Epoxy                              |                                       |
| ④<br>ボンディングワイヤ<br>Bonding wire | Au   |                                       |
| ⑤<br>シリコンチップ<br>Silicon chip   | Si   |                                       |

|                 |                       |
|-----------------|-----------------------|
| 捺印表示<br>Marking | レーザー<br>Laser marking |
|-----------------|-----------------------|